



PK456 (v1.0) January 28,  
2011

## 100% Material Declaration Data Sheet FG1156

**Average Weight: 5.6250 g**

Component	Substance Description	CAS# or Description	% of Component	Use in Product	Component Weight/ Substance Weight (in grams)	Component % of Total
<b>Silicon Die</b>					<b>0.256153</b>	<b>4.554%</b>
	Silicon	7440-21-3	100.00		0.256153	
<b>Die Attach Material</b>					<b>0.072582</b>	<b>1.290%</b>
	Silver	7440-22-4	77.50		0.056251	
	Bismaleimide monomer	Trade Secret	15.00		0.010887	
	Acrylate monomer	Trade Secret	7.50		0.005444	
<b>Mold Compound</b>					<b>2.292107</b>	<b>40.749%</b>
	Epoxy Resin A	Trade Secret	3.00		0.068763	
	Epoxy Resin B	Trade Secret	3.00		0.068763	
	Phenol Resin A	Trade Secret	3.00		0.068763	
	Phenol Resin B	Trade Secret	3.00		0.068763	
	Metal Hydroxide	Trade Secret	1.50		0.034382	
	Carbon Black	1333-86-4	0.30		0.006876	
	Silica Fused	60676-86-0	70.90		1.625104	
	Silica Fused	7631-86-9	15.00		0.343816	
	Silica, crystalline	14808-60-7	0.30		0.006876	
<b>Gold Wire</b>					<b>0.029878</b>	<b>0.531%</b>
	Gold	7440-57-5	99.05		0.029594	
	Palladium	7440-05-3	0.95		0.000284	
	Calcium	7440-70-2	0.00		0.000001	
<b>Solder Balls</b>					<b>1.100277</b>	<b>19.560%</b>
	Tin	7440-31-5	63.00		0.693175	
	Lead	7439-92-1	37.00		0.407102	

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Substrate					<b>1.874003</b>	<b>33.316%</b>
	Copper (Cu)	7440-50-8	37,36		0.700097	
	Nickel (Ni)	7440-02-0	3.96		0.074124	
	Gold (Au)	7440-57-5	0.47		0.008863	
	Epoxy resin	NA	22.11		0.414407	
	Inorganic filler	21645-51-2	7.86		0.147217	
	Continuous filament fiber glass	65997-17-3	19.90		0.372951	
	Copper (Cu)	7440-50-8	2.62		0.049072	
	Talc	14807-96-6	0.29		0.005364	
	Morpholine derivative	NA	0.17		0.003218	
	Barium Sulfate	7727-43-7	2.52		0.047199	
	Silica	7631-86-9	0.06		0.001073	
	Dipropylene Glycol Monomethyl Ether	34590-94-8	1.49		0.027891	
	Epoxy resin	85954-11-6	1.20		0.022527	

## Revision History

The following table shows the revision history for this document.

Date	Version	Description of Revisions
01/28/11	1.0	Initial Xilinx release.

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